

Bill of Materials

TI DESIGNS
TIDA-00830

Item	Qty	Reference	Part Description	Manufacturer	Manufacturer Part Number
1	1	!PCB1	Printed Circuit Board	Any	00830
2	3	C1, C4, C5	CAP, CERM, 0.1 μ F, 100 V, +/-	Kemet	C0805C104K1RACTU
3	1	C2	CAP, AL, 100 μ F, 63 V, +/- 20%, 0.35 ohm, SMD	Panasonic	EEE-FK1J101P
4	1	C3	CAP, CERM, 0.47 μ F, 25 V, +/- 10%, X7R, 0805	TDK	C2012X7R1E474K
5	1	C6	CAP, CERM, 0.47 μ F, 6.3 V, +/- 10%, X7R, 0603	Kemet	C0603C474K9RACTU
6	6	C7, C8, C9, C10, C11, C14	CAP, CERM, 0.1 μ F, 10 V, +/-	MuRata	GRM155R61A104KA01D
7	1	C12	CAP, CERM, 4.7 μ F, 10 V, +/-	TDK	CGB3B1X5R1A475K055AC
8	1	C13	CAP, CERM, 1 μ F, 10 V, +/- 10%,	MuRata	GRM155R61A105KE15D
9	1	D1	LED, Red, SMD	Lite-On	LTST-C190CKT
10	1	D2	LED, Green, SMD	Lite-On	LTST-C190GKT
11	3	J1, J2, J4	Terminal Block, 6A, 3.5mm Pitch,	On-Shore Technology	ED555/2DS
12	2	J3, J7	Header, 100mil, 2x1, Tin, TH	Molex	90120-0122
13	1	J6	Header, 100mil, 18x1, Gold, TH	Samtec	TSW-118-07-G-S
14	1	J8	Header, 100mil, 7x2, Tin, TH	Sullins Connector Solutions	PEC07DAAN
15	1	J9	Connector, Receptacle, Micro-USB Type B, R/A, Bottom Mount SMT	Hirose Electric Co. Ltd.	ZX62-B-5PA(11)

Item	Qty	Reference	Part Description	Manufacturer	Manufacturer Part Number
16	1	L1	Ferrite Bead, 30 ohm @ 100 MHz, 1.5 A, 0805	TDK	MMZ2012R300A
17	1	LBL1	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	Brady	THT-14-423-10
18	2	R1, R2	RES, 0.25, 1%, 1 W, 2010	Stackpole Electronics Inc	CSRN2010FKR250
19	2	R3, R4	RES, 33, 5%, 0.0625 W, Resistor Array - 8x1	Panasonic	EXB-2HV330JV
20	1	R5	RES, 510, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402510RJNED
21	1	R6	RES, 4.99 k, 1%, 0.063 W, 0402	Vishay-Dale	CRCW04024K99FKED
22	1	R7	RES, 330, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402330RJNED
23	2	R8, R10	RES, 0, 5%, 0.063 W, 0402	Panasonic	ERJ-2GE0R00X
24	1	R9	RES, 3.32 k, 1%, 0.063 W, 0402	Vishay-Dale	CRCW04023K32FKED
25	1	S1	Switch, Tactile, SPST-NO, 0.05A,	Panasonic	EVQP1D05M
26	6	TP1, TP2, TP3, TP4, TP5,	Test Point, Compact, SMT	Keystone	5016
27	1	TP7	1mm Uninsulated Shorting Plug, 10.16mm spacing, TH	Harwin	D3082-05
28	1	U1	2-A 45-V 1/16- μ step Stepper Motor Driver With AutoTune, PWP0028C	Texas Instruments	DRV8880PWPR
29	1	U2	16 MHz Mixed Signal Microcontroller with 92 KB Flash, 8192 B SRAM and 48 GPIOs, -40 to 105 degC, 64-pin QFP (PM), Green (RoHS & no Sb/Br)	Texas Instruments	MSP430F2617TPM
30	1	U3	USB to Serial UART, SSOP28	FTDI	FT232RL

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